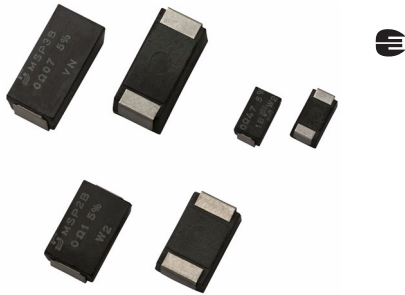


Precision Surface Mount Resistors Wirewound or Metal Film Technologies



FEATURES

- Approved according CECC 40402-801 (wirewound)
- Wide range of ohmic values (0.04 Ω to 1 MΩ)
- Low temperature coefficient (± 25 ppm/°C available)
- Good electrical insulation
- All welded construction and molded encapsulant
- High power ratings (up to 2.5 W)
- Stability class 0.5
- Pure matte tin termination
- Compliant to RoHS directive 2002/95/EC



RoHS
COMPLIANT

Specially designed for surface mounting, the MSP series uses either wirewound or metal film technology. The molded package ensures mechanical and climatic protection as well as high dielectric insulation. The MSP design is compatible with surface mounting equipment and can withstand wave and reflow soldering techniques.

DIMENSIONS in millimeters										
SERIES AND STYLES	A	B	C	D	E	F	W	X	Z	AVERAGE MASS (g)
MSP 1	6.9	3.8	3.8	2.5	6.5	1.4	2.7	2.9	6	0.2
MSP 2	11.4	5	7	5	11	2.4	5.2	4.1	9.4	0.8
MSP 3	14.8	6.6	7	5	14.4	2.4	5.2	4.1	12.7	1.5

Note

- General tolerance: ± 0.2 mm

TECHNICAL SPECIFICATIONS						
RESISTIVE TECHNOLOGY		WIREWOUND			METAL FILM	
Vishay Sfernice Series CECC 40402-801 Metric Size		MSP 1 B RW1	MSP 2 B RW2	MSP 3 B RW3	MSP 1 C -	MSP 2 C -
Rated Dissipation at + 25 °C, P ₂₅		1 W	2 W	2.5 W	0.5 W	1 W
Ohmic Range in Relation to Tolerance (with Preferred Ohmic Value Series)	± 5 % E24 Series	0.04 to 2.2K	0.04 to 4.7K	0.04 to 13K	-	-
	± 2 % E48 Series	0.04 to 2.2K	0.04 to 4.7K	0.05 to 13K	-	-
	± 1 % E96 Series	0.04 to 2.2K	0.04 to 4.7K	0.05 to 13K	10 to 332K	10 to 1M
	± 0.5 % E96 Series	0.4 to 2.2K	0.4 to 4.7K	0.3 to 13K	10 to 332K	10 to 1M
	± 0.1 % E192 Series	-	-	-	10 to 332K	10 to 332K
Approved Range CECC 40402-801	1 % or Class 0.5	0.5 to 1K	0.5 to 2.2K	0.1 to 4.12K	-	-
Limiting Element Voltage, U _{max.} AC/DC		50 V	120 V	200 V	300 V	350 V



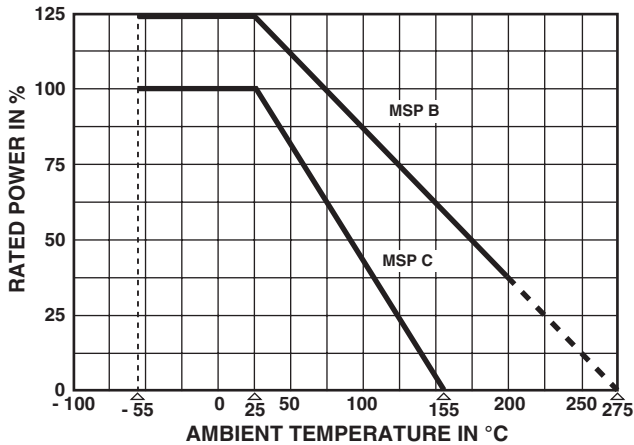
TECHNICAL SPECIFICATIONS (continued)					
RESISTIVE TECHNOLOGY	Wirewound			Metal Film	
Series	MSP 1 B	MSP 2 B	MSP 3 B	MSP 1 C	MSP 2 C
Critical Resistance	-	-	-	180K	122.5K
Temperature Coefficient	CECC 40402-801 - 55 °C/+ 200 °C < 1 Ω ± 100 ppm/°C 1 Ω to < 10 Ω ± 50 ppm/°C ≥ 10 Ω ± 25 ppm/°C			- 55 °C/+ 155 °C 10 kΩ to 332 kΩ K3: ± 50 ppm/°C K4: ± 25 ppm/°C > 332 kΩ K3: ± 50 ppm/°C	
Failure Rate with CECC Approval	E6 10 ⁻⁶ /h	E6 10 ⁻⁶ /h	E0 or A 10 ⁻⁴ /h	-	-

MECHANICAL SPECIFICATIONS		
RESISTIVE TECHNOLOGY	Wirewound	Metal Film
Encapsulant	Thermoset	
Resistive Element	CuNi or NiCr	NiCr or NiP
Ceramic Substrate	Alumina or Steatite	Alumina
Termination	Electrolytic pure matte tin	

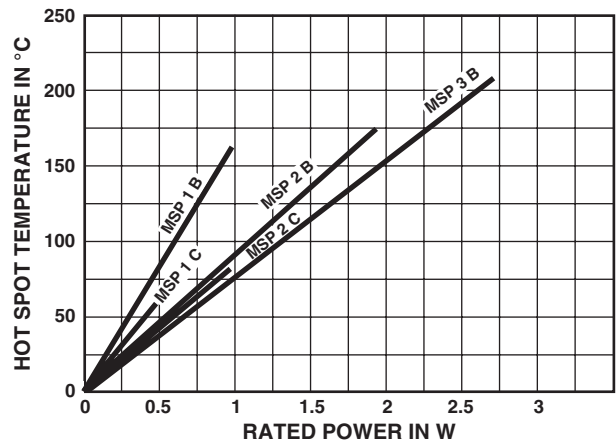
ENVIRONMENTAL SPECIFICATIONS		
RESISTIVE TECHNOLOGY	Wirewound	Metal Film
Temperature Range	- 55 °C to 275 °C	- 55 °C to 155 °C
Climatic Category (LCT/UCT/days)	55/200/56	55/125/10

PERFORMANCE				
TESTS	CONDITIONS		REQUIREMENTS	
	Wirewound	Metal Film	Wirewound CECC 40402-801	Metal Film
Short Time Overload	IEC 60115-1 5 P _r or U = 2 U _{max} /5 s		± (0.25 % + 0.05 Ω)	± 0.25 %
Load Life	IEC 60115-1 90'/30' cycles 1000 h P _r + 25 °C 8000 h P _r		± (0.5 % + 0.05 Ω) ± (3 % + 0.05 Ω)	± 1 % -
Dielectric w/s Voltage	IEC 60115-1 U _{RMS} = 500 V/60 s		No flashover or breakdown Leakage current < 10 μA	
Rapid Change of Temperature	IEC 60115-1 IEC 60068-2-14 Test Na 5 cycles (30' at LCT/30' at UCT) - 55 °C/+ 200 °C - 55 °C/+ 125 °C		± (0.25 % + 0.05 Ω)	± 0.25 %
Climatic Sequence	IEC 60115-1 - 55 °C/+ 200 °C - 55 °C/+ 125 °C		± (0.5 % + 0.05 Ω)	± 0.5 %
Humidity (Steady State)	IEC 60115-1 IEC 60068-2-3 Test Ca 95 % HR/40 °C 56 days 10 days		± (0.5 % + 0.05 Ω)	± 1 %
Substrate Bending Test	IEC 60115-1 IEC 60068-2-21 Test U _{e3} 2 mm/10 times		± (0.25 % + 0.05 Ω)	± 0.25 %
Shock	IEC 60115-1 IEC 60068-2-27 Test Ea 50 g's/half sine/3 times by direction (i.e. 18 shocks)		± (0.25 % + 0.05 Ω)	N/A
Vibration	IEC 60115-1 IEC 60068-2-6 Test Fc 10 Hz/2000 Hz 10 Hz/500 Hz		± (0.25 % + 0.05 Ω)	± 0.25 %
Resistance to Soldering Heat	IEC 60115-1 IEC 60068-2-58 Solder bath 260 °C/10 s		± (0.5 % + 0.05 Ω)	N/A

POWER RATING



TEMPERATURE RISE



SURFACE MOUNTING OF MSP B

Soldering cycle: 2 min at 215 °C or 10 s at 260 °C or with an iron 40 W: 3 s at 350 °C.
Soldering is possible by wave, reflow and vapor phase.

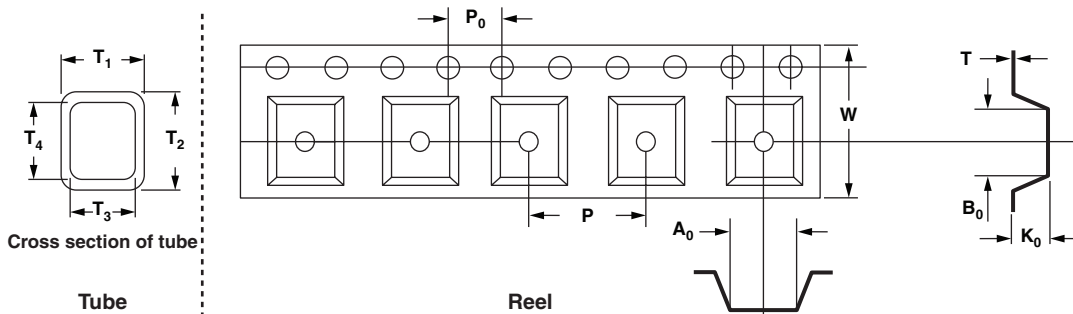
NON INDUCTIVE WINDING FOR MSP B

Non inductive (Ayrton Perry) winding available.
Please consult Vishay Sfernice.

PACKAGING

In bulk (plastic bag of 100 units or multiples)
In tube: MSP1 70 units per tube
MSP2 50 units per tube
MSP3 40 units per tube
In reel of 500 units for MSP1 and MSP2

DIMENSIONS in millimeters - Informative Data



	TUBE PACKAGING					REEL PACKAGING						
	T ₁	T ₂	T ₃	T ₄	Length	A ₀	B ₀	K ₀	P ₀	W	T	P
MSP 1	6.6	6.8	4.6	4.8	530	3.9	7.35	4.25	4	12	0.254	8
MSP 2	9.2	8.7	8	7.5	615	7.43	11.91	5.36	4	24	0.368	12
MSP 3						N/A						

MARKING

Vishay Sfernice trademark, ohmic value (in Ω), tolerance (in %), series and style, technology, manufacturing date.



ORDERING INFORMATION								
MSP	1	B		48U7	± 1 %	TC	BA100	e3
SERIES	STYLE	TECHNOLOGY	NON INDUCTIVE WINDING	OHMIC VALUE	TOLERANCE	Applicable only in "C" technology	PACKAGING	LEAD (Pb)-FREE
		B: Wirewound C: Metal Film	Optional					

SAP PART NUMBERING GUIDELINES																	
M	S	P		1	B	4	8	R	7	0	F		T	2	0	E	3
GLOBAL MODEL	OPTION	SIZE	OHMIC VALUE				TOL.	TEMP. COEF.	PACKAGING	SPECIAL	RoHS						
MSP	Blank or N (Non inductive winding)	1B 2B 3B 1C 2C B = Wirewound C = Metal film	The first four digits are significant figures and the last digit specifies the number of zeros to follow. R designates decimal point. 48R70 = 48.7 Ω 48701 = 48 700 Ω 10002 = 100 000 Ω R0100 = 0.01 Ω R4700 = 0.47 Ω ...				B = 0.1 % F = 1 % G = 2 % J = 5 % K = 10 %	Blank or Applicable only on metal film technologies 1C and 2C: E ≥ K3 or H ≥ K4	S14 = Bag (100 pieces) R10 = Reel (500 pieces) T25 = Tube (70 pieces) T17 = Tube (40 pieces) T20 = Tube (50 pieces)	As applicable	E3 = Pure tin						



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